Thermosetting tapes suitable such as specialty card (Metal card or biometric card, Dynamic card verification value card)

# D3450 series Thermosetting Tapes for smart cards

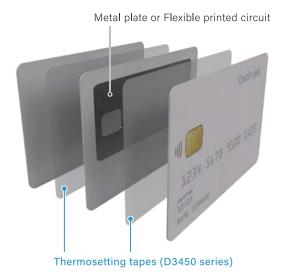


Product Name D3451 D3450

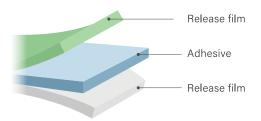
#### Features

- Excellent adhesive strength for plastic sheet, metal plate & flexible printed circuit by hot lamination
- Storage at room temperature; easy handling.
- Initial tack enables tentative positioning

### Example of Use



#### Structure



## **Specifications**

Product name	D3450	D3451	
Main component	Acrylic / Epoxy	Acrylic / Epoxy	
Carrier	Non-carrier	Non-carrier	
Color	White	White	
Adhesive thickness [µm]	About 35	About 25	
Release film thickness [µm]	About 38	About 38	
Release paper thickness [µm]	About 130	About 130	
Bonding strength [N/10mm] *	31	25	
Standard size (width & length)	250mm x 100m 500mm x 100m	250mm x 100m 500mm x 100m	

## [ Standard bonding condition ]

■ Vacuum quick press and postcure process
Press temperature: 160 to 180 °C
Vacuum time: 10 to 30 sec
Pressing time: 1 to 2 min.
Pressure: 1 to 2 MPa

Postcure condition : 140°C 60min.

■ Long press process Press temperature: 160 °C Pressing time: 60 min. Pressure: 3 MPa

<sup>\* 90°</sup> peeling strength / Substrate : Polyimide

### Technical data

#### Bonding strength on various type of substrate (90°peeling)

(N/10mm)

Bonding	Substrate	D3450		D3451	
condition		Normal	After reflow	Normal	After reflow
Vacuum quick press and postcure	CCL/Polyimide	31	31	31	31
	CCL/Glass epoxy	27	27	27	27
	CCL/Aluminum	16	16	16	16
	CCL/Stainless steel	17	17	17	17
Long Press	CCL/Polyimide	26	26	26	26
	CCL/Glass epoxy	28	28	28	28
	CCL/Aluminum	16	16	16	16
	CCL/Stainless steel	18	18	18	18

#### [ Test piece condition ]

Substrate: Glass Epoxy, Polyimide, Aluminum, Stainless steel

Tape width: 10mm

Bonding condition: recommended processes
Measuring condition: 23°C±5°C 60%±20%RH

Peeling speed: 50mm/min

Backing material: CCL (Copper Clad Laminate)

